

## Features

- Transient protection for high-speed data lines
  - IEC 61000-4-2 (ESD) ±25kV (Air)  
±15kV(Contact)
  - IEC 61000-4-4 (EFT) 40A  
(5/50 ns) Cable Discharge Event (CDE)
- Package optimized for high-speed lines
- Ultra-small package (1.0mm×0.6mm×0.55mm)
- Protects one data, control or power line
- Low capacitance: 0.5pF (Typical)
- Low leakage current: 0.1uA @ V<sub>RWM</sub> (maximum)
- Low clamping voltage
- Each I/O pin can withstand over 1000 ESD strikes for ±8kV contact discharge
- ROHS compliant

## Description

TE0501SBX is a low -capacitance Transient Voltage Suppressor (TVS) designed to provide electrostatic discharge (ESD ) protection for high -speed data interfaces. With typical capacitance of 0.5 pF only,

TE0501SBX is designed to protect parasitic - sensitive systems against over-voltage and over-current transient events. It complies with IEC 61000-4-2 (ESD), Level 4 (±15kV air, ±8kV contact discharge), IEC 61000-4-4 (electrical fast transient - EFT) (40A, 5/50 ns), very fast charged device model (CDM ) ESD and cable discharge event (CDE), etc.

TE0501SBX uses ultra-small DFN1006 package. Each TE0501SBX device can protect one high -speed data line. It offers system designers flexibility to protect single data line where space is a premium concern. The combined features of low capacitance, ultra-small size and high ESD robustness make TE0501SBX ideal for high -speed data port and high -frequency line (e.g., USB 2.0 & antenna line) applications, such as cellular phones and HD visual devices.

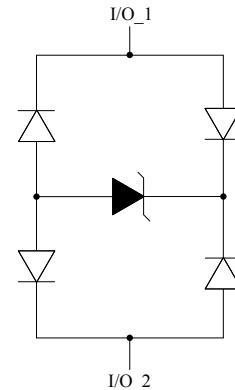
## Applications

- Serial ATA
- PCI Express
- Desktops, Servers and Notebooks
- Cellular Phones
- MDDI Ports
- USB2.0/3.0 Power and Data Line
- Display Ports
- Digital Visual Interfaces (DVI)
- HDMI 1.4/2.0

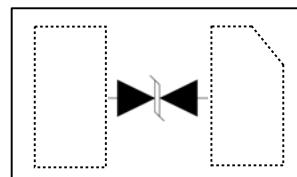
## Mechanical Characteristics

- DFN1006 package
- Flammability Rating: UL 94V-0
- Packaging: Tape and Reel

## Circuit Diagram



## Pin Configuration



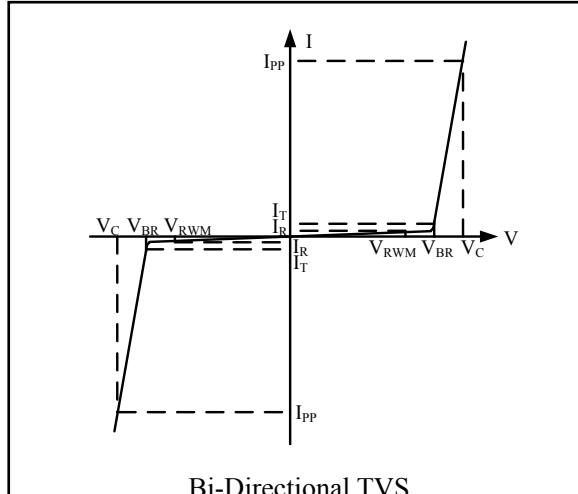
DFN1006-2L  
(Top View)

## Absolute Maximum Rating

Symbol	Parameter	Value	Units
I <sub>PP</sub>	Peak Pulse Current(tp=8/20us)	3	A
V <sub>ESD</sub>	ESD per IEC 61000-4-2(Air) ESD per IEC 61000-4-2 (Contact)	±25 ±15	kV
T <sub>OPT</sub>	Operating Temperature	-55/+125	°C
T <sub>STG</sub>	Storage Temperature	-55/+150	°C

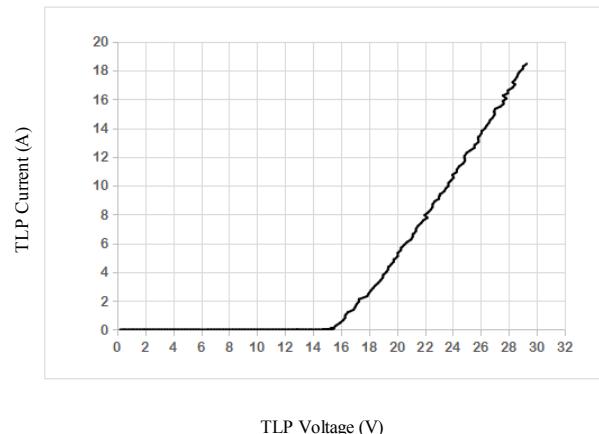
## Electrical Characteristics(T<sub>A</sub>=25°C)

Symbol	Parameter
V <sub>RWM</sub>	Nominal Reverse Working Voltage
I <sub>R</sub>	Reverse Leakage Current @ V <sub>RWM</sub>
V <sub>BR</sub>	Reverse Breakdown Voltage @ I <sub>T</sub>
I <sub>T</sub>	Test Current for Reverse Breakdown
V <sub>C</sub>	Clamping Voltage @ I <sub>PP</sub>
I <sub>PP</sub>	Peak Pulse Current
C <sub>ESD</sub>	Parasitic Capacitance
V <sub>R</sub>	Reverse Voltage
f	Small Signal Frequency

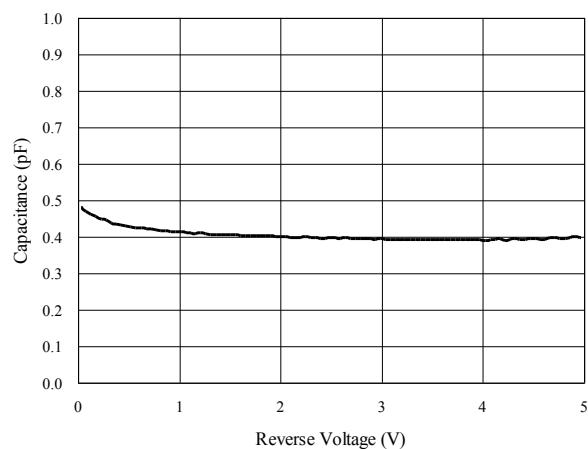


Symbol	Test Condition	Minimum	Typical	Maximum	Units
V <sub>RWM</sub>				5.0	V
I <sub>R</sub>	V <sub>RWM</sub> = 5V, T = 25°C Between I/O and I/O			0.1	µA
V <sub>BR</sub>	I <sub>T</sub> = 1mA Between I/O and I/O	13		17	V
V <sub>C</sub>	I <sub>PP</sub> = 1A, t <sub>p</sub> = 8/20µs Between I/O and I/O			19	V
V <sub>C</sub>	I <sub>PP</sub> = 3A, t <sub>p</sub> = 8/20µs Between I/O and I/O			22	V
C <sub>ESD</sub>	V <sub>R</sub> = 0V, f = 1MHz Between I/O and I/O		0.50		pF

## TLP Measurement of I/O\_1 to I/O\_2

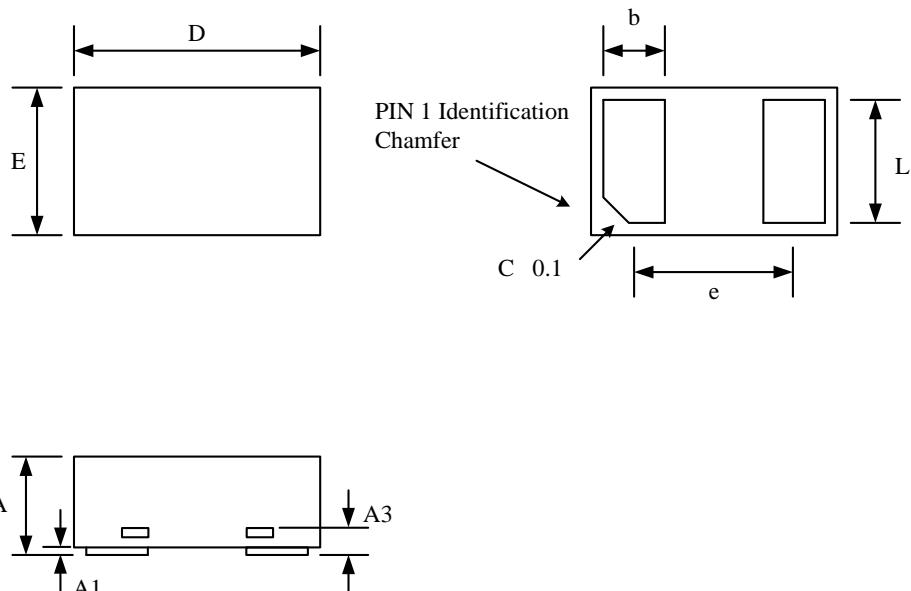


## Capacitance vs. Reverse Voltage



## Package Outline

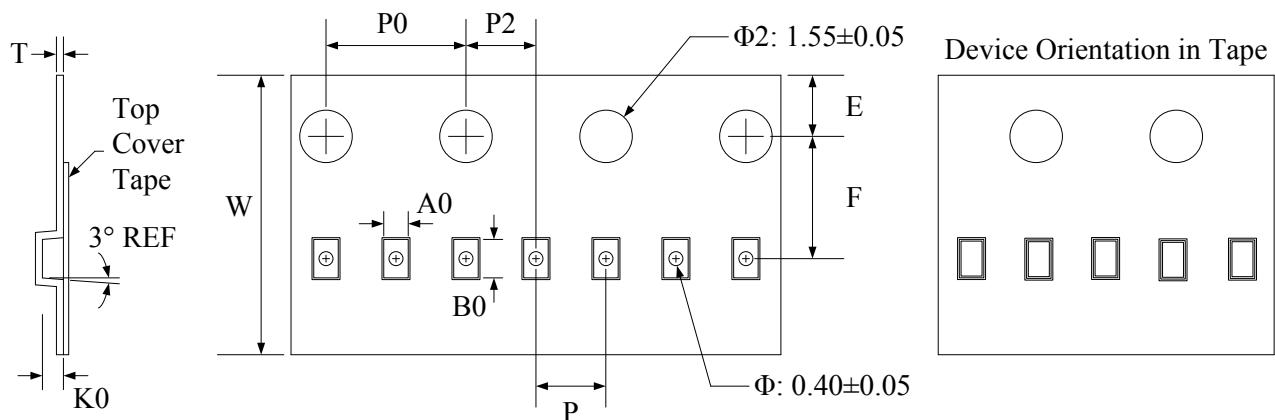
- DFN1006-2L Package
- MSL-1



Package Dimensions (Controlling dimensions are in millimeters)

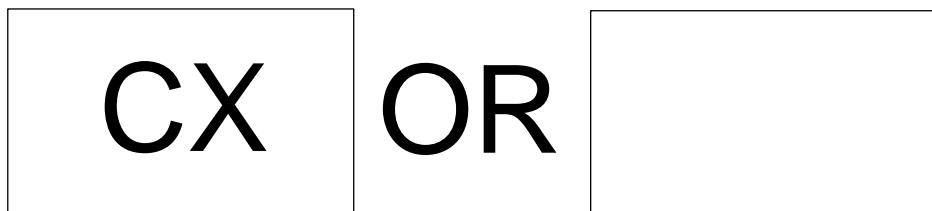
Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Minimum	Maximum	Minimum	Maximum
A	0.400	0.550	0.016	0.022
A1	0.000	0.050	0.000	0.002
A3	0.125 REF		0.005 REF	
D	0.950	1.050	0.037	0.041
E	0.550	0.650	0.022	0.026
b	0.200	0.300	0.008	0.012
e	0.650 BSC		0.026 BSC	
L	0.450	0.550	0.018	0.022

## Tape and Reel Specification



Symbol	W	A0	B0	K0	E	F	P	P0	P2	T
Dimensions (mm)	8.00±0.1	0.7±0.05	1.15±0.05	0.55±0.05	1.75±0.1	3.5±0.05	2.0±0.1	4.0±0.1	2.0±0.05	0.2±0.05

## Marking Codes



- (1) "C" is part number, fixed.
- (2) "X" is the internal code.